

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

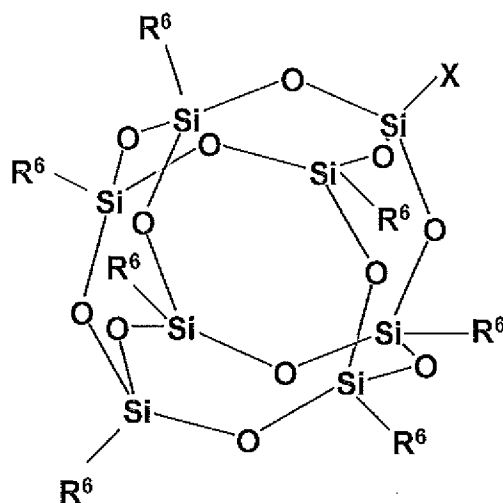
Claims 1-22 (canceled).

Claim 23 (currently amended). A complex of (i) an organoboron compound of the general formula (I):



in which each R^1 independently represents an alkyl group, an aryl group, an alkylaryl group, an arylalkyl group, a cycloalkyl group, an alkylcycloalkyl group or a cycloalkylalkyl group each of which may be unsubstituted or substituted by one or more of the same or different substituents selected from halogen atoms and alkoxy groups

and (ii) a silsesquioxane containing at least one primary, secondary and/or tertiary amino group of the formula



wherein R^6 is hydrogen or an alkyl or phenyl group optionally substituted by one or more primary or secondary amino groups, and X is $-R^3-NH_2$ wherein R^3 is an alkyl group.

Claim 24 (previously presented). The complex as claimed in claim 23, in which each R¹ independently represents a C₁₋₁₀ alkyl group.

Claim 25 (previously presented). The complex as claimed in claim 24, wherein each R¹ is independently selected from the group consisting of an ethyl group, isopropyl group, *t*-butyl group and *n*-butyl group.

Claims 26-31 (cancelled).

Claim 32 (withdrawn). A method of initiating the polymerization of a polymerizable monomer or oligomer by contacting the monomer or oligomer with a complex of (i) an organoboron compound of the general formula (I):



in which each R¹ independently represents an alkyl group, an aryl group, an alkylaryl group, an arylalkyl group, a cycloalkyl group, an alkylcycloalkyl group or a cycloalkylalkyl group each of which may be unsubstituted or substituted by one or more of the same or different substituents selected from halogen atoms and alkoxy groups

and (ii) an organosilicon compound containing at least one primary, secondary and/or tertiary amino group and optionally supplying energy in the form heat, actinic radiation, electromagnetic radiation, magnetic radiation, electrical current, ultrasound, ultraviolet radiation or combinations thereof sufficient to release the boron compound from the complex.

Claim 33 (withdrawn). A method of adhesively bonding two substrates together comprising the steps of applying a polymerizable composition comprising a polymerizable monomer or oligomer and a complex of (i) an organoboron compound of the general formula (I):



in which each R¹ independently represents an alkyl group, an aryl group, an alkylaryl group, an arylalkyl group, a cycloalkyl group, an alkylcycloalkyl group or a cycloalkylalkyl group each of

which may be unsubstituted or substituted by one or more of the same or different substituents selected from halogen atoms and alkoxy groups

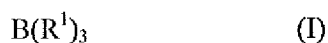
and (ii) an organosilicon compound containing at least one primary, secondary and/or tertiary amino group to a first substrate; positioning a second substrate in contact with the first substrate; and curing the polymerizable composition.

Claim 34 (withdrawn). The method of claim 33, wherein at least one of the substrates is a low surface energy substrate.

Claim 35 (withdrawn). The method of claim 34, wherein the low surface energy substrate comprises a material selected from polyethylene, polypropylene, copolymers of α -olefins, and fluorinated polymers.

Claim 36 (withdrawn). The method of claim 33, wherein the surface of at least one of the substrates comprises a material selected from the group of thermoplastics, thermosets, wood, composites, ceramics, glass, concrete, and metals.

Claim 37 (withdrawn). A polymerisable composition comprising at least one radically polymerisable monomer and/or oligomer and a complex of (i) an organoboron compound of the general formula (I):



in which each R^1 independently represents an alkyl group, an aryl group, an alkylaryl group, an arylalkyl group, a cycloalkyl group, an alkylcycloalkyl group or a cycloalkylalkyl group each of which may be unsubstituted or substituted by one or more of the same or different substituents selected from halogen atoms and alkoxy groups

and (ii) an organosilicon compound containing at least one primary, secondary and/or tertiary amino group.

Claim 38 (withdrawn). The polymerisable composition of claim 37, which further comprises at least one of a reactive or non-reactive diluent, a decomplexing agent and an open time extender.

Claim 39 (withdrawn). The polymerisable composition of claim 37, which further comprises one or more fillers.

Claim 40 (withdrawn). The polymerisable composition of claim 37 which further comprises trimethylolpropane tris(2-methyl-1-aziridinepropionate).

Claim 41 (withdrawn). The polymerisable composition of claim 37 which further comprises at least one heat management material.

Claim 42 (withdrawn). The polymerisable composition of claim 37, in which the concentration of the complex is sufficient to provide 0.001% to 10.0% by weight of boron, based on the total weight of the polymerisable composition.

Claim 43 (withdrawn). A 2 part composition comprising:

(1) a silicon-amino organo-borane complex comprising an organoboron compound of the general formula (I):



in which each R^1 independently represents an alkyl group, an aryl group, an alkylaryl group, an arylalkyl group, a cycloalkyl group, an alkylcycloalkyl group or a cycloalkylalkyl group each of which may be unsubstituted or substituted by one or more of the same or different substituents selected from halogen atoms and alkoxy groups

and an organosilicon compound containing at least one primary, secondary and/or tertiary amino group; and

(2) a blend of radically polymerisable compounds, at least one decomplexing agent; and optionally at least one open time extender and/or toughener material.